

**REMARKS**

Claims 1-34 are pending in this application. By the Office Action, claims 5-34 are withdrawn from consideration; claim 1 is rejected under 35 U.S.C. §112, second paragraph; and claims 1-4 are rejected under 35 U.S.C. §103(a). By this Amendment, claim 1 is amended. Support for the amendments to claim 1 can be found, for example, in the specification and Figures as filed. No new matter is added. In view of the foregoing amendments and following remarks, reconsideration and allowance are respectfully requested.

**I. Rejection under 35 U.S.C. §112, Second Paragraph**

The Office Action rejects claim 1 under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. By this Amendment, claim 1 is amended in light of the Examiner's comments.

Without conceding the propriety of the rejections, independent claim 1 is amended to more clearly recite various novel features of the claimed invention, with particular attention to the Examiner's comments. Specifically, claim 1 is amended to clarify that "...the contact surfaces of the inner terminals are included in one plane, the upper surfaces of the outer terminals are included in another plane, the lower surfaces of the outer terminals of the terminal members are included in a third plane, respectively... ."

Accordingly, reconsideration and withdrawal of the rejection are respectfully requested.

**II. Rejection Under 35 U.S.C. §103(a)**

The Office Action rejects claims 1-4 under 35 U.S.C. §103(a) over Huang in view of Yagi. Applicants respectfully traverse the rejection.

Claim 1, as amended, is directed to a plastic package comprising: a plurality of terminal members each having an outer terminal having an upper surface, a lower surface and an outer side surface, an inner terminal having a contact surface, and a connecting part connecting the outer and the inner terminal; a semiconductor device provided with terminal pads connected to the contact surfaces of the inner terminals with bond wires; and a resin molding sealing the terminal members, the semiconductor device and the bond wires therein. Claim 1 further specifies that the inner terminals of the terminal members are thinner than the outer terminals and have the contact surfaces, the contact surfaces of the inner terminals, the upper surfaces of the outer terminals, the lower surfaces of the outer terminals of the terminal members are included in different planes, respectively, and the upper, the lower and the outer side surfaces of the outer terminals of the terminal members, and a surface of the semiconductor device opposite the surface provided with the terminal pads are exposed outside, and the inner terminals, the bond wires, the semiconductor device and the resin molding are included in the thickness of the outer terminals, wherein the inner terminal is located closer to the semiconductor device than the outer terminal, and the inner terminal has a half-etched upper surface lower than the upper surface of the outer terminal so that the thickness of the inner terminal is thinner than that of the outer terminal, and the semiconductor device has a thickness thinner than that of the inner terminals, and each inner terminal is so constructed that the section of the inner terminal is tapered toward the inside. Such a plastic package semiconductor device is nowhere taught or suggested by the cited references.

The Office Action admits that Huang fails to teach the semiconductor device provided with terminal pads, and wherein the semiconductor device has a thickness thinner than that of the inner terminals, and each inner terminal is so constructed that the section of the inner terminal is tapered toward the inside. *See* October 29, 2007 Office Action, page 4, lines 16-

19. However, the Office Action argues that Yagi discloses a semiconductor device that is thinner than the inner terminals, and each inner terminal is so constructed that the section of the inner terminal is tapered toward the inside, and it would have been obvious to combine Yagi's teachings with Huang. Applicants disagree that the cited references would have rendered obvious the claimed invention.

According to claim 1 as amended herein, the claimed invention includes, *inter alia*, the following features:

- (1) each inner terminal is bent toward the corresponding terminal pad in a plan view;
- (2) the inner terminals on both the end sides have a tapered shape in a plan view; and
- (3) the section of the inner terminal is tapered toward the inside to leave a tip on the half-etched upper surface.

As a result of these features, the claimed invention provides significant advantages to the plastic package that are not taught or suggested by the cited references.

As a result of a combination of the above features (1)-(3), the inner terminal can be easily and securely connected to the corresponding terminal pad with a bond wire since the inner terminal is bent toward the corresponding terminal pad in a plan view. In addition, since the inner terminals on both the end sides have a tapered shape in a plan view, all of the terminal members can be compactly arranged in a plan view. Furthermore, because the section of each terminal is tapered toward the inside to leave a tip on the half-etched upper surface, the adhesive strength between the inner terminal and the resin molding can be increased.

Neither Huang or Yagi, alone or in combination, teach or suggest these benefits, or the means to accomplish these benefits. None of the references teach that each inner terminal is bent toward the corresponding terminal pad in a plan view, or that the inner terminals on both the end sides have a tapered shape in a plan view. Moreover, while Huang and Yagi allegedly

teach that the section of the inner terminal is tapered toward the inside, neither teach or suggest that the section of each inner terminal is tapered toward the inside to leave a tip on the half-etched upper surface.

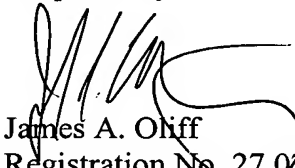
As Huang and Yagi fail to teach or suggest at least these features of the claimed invention, and the benefits provided thereby, the references alone or in combination would not have rendered obvious the claimed invention. Claim 1, and its dependent claims, would thus not have been rendered obvious by Huang and Yagi. Accordingly, reconsideration and withdrawal of the rejection are respectfully requested.

### **III. Conclusion**

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of the application are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,

  
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Attachment:  
Petition for Extension of Time

Date: February 20, 2008

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